

PCB capability

Layers:	1-22 layers
Thicker Copper:	0.5-6OZ
Material:	FR4(Shengyi China,ITEQ,KB A+,HZ),HI-TG, FR06,Rogers, Taconic,Argon,Nalco,Isola and so on
Solder Mask:	green, yellow,white, blue,black,red
Finished Surface:	conventional hasl, lead free hasl, immersion gold, immersion tin,
	immersion silver, hard gold, OSP...
Silkscreen color:	white
Products Type:	HF(High-Frequency)&(Radio Frenquency)board,
	impedance controlled board, HDI board,BGA&Fine pitch board
Minimum line width/gap:	3.5/4mil(laser drill)
Minimum hole size:	0.15mm(mechanical drill)/4mil(laser drill)
Minimum Annlar Ring:	4mil
Max Copper thickness:	6OZ
Min Solder Mask Bridge:	0.08mm
Plugging Vias capability:	0.2-0.8mm

Delivery Time

layer	Prototype		Mass productions (above 30 m2)
	quick turn	unual time	
2	24 hours	3-4 days	8-10 days
4	48 hours	5-6 days	10-12 days
6	72 hours	6-8 days	12-14 days
8	72 hours	8-10 days	16-18 days
10	96 hours	12-12 days	18-20 days
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